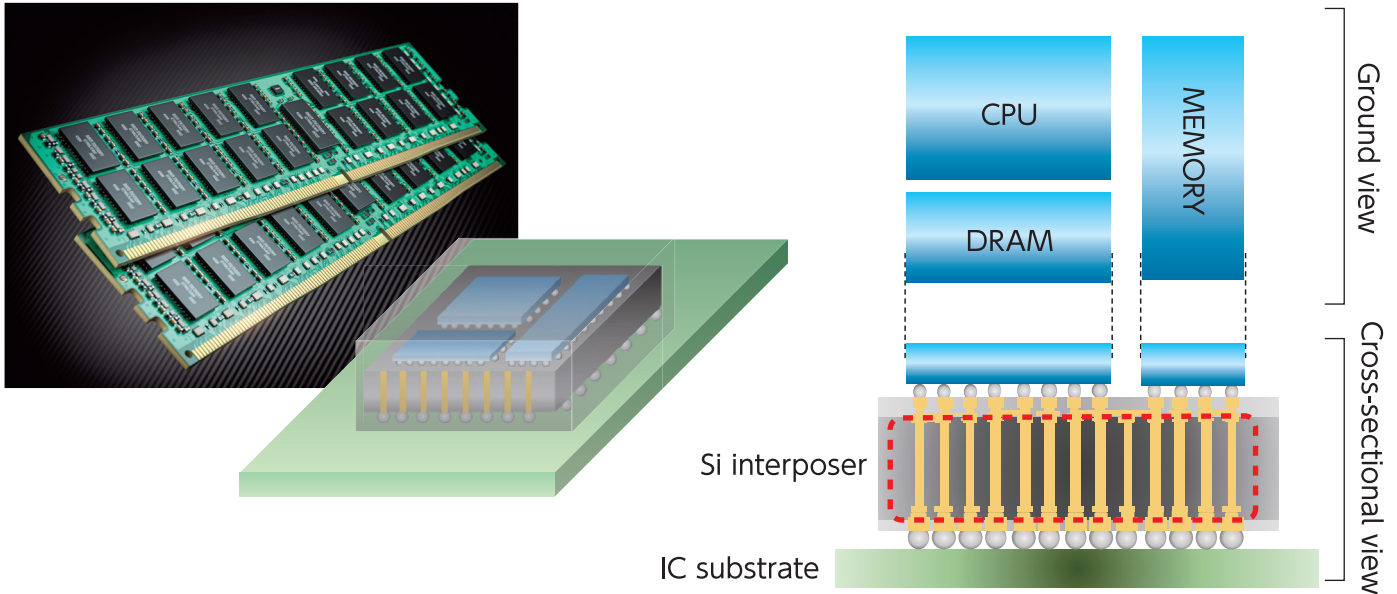
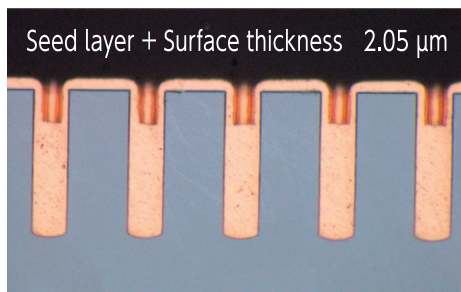


Acid copper plating additive to silicon interposer for high aspect ratio filling

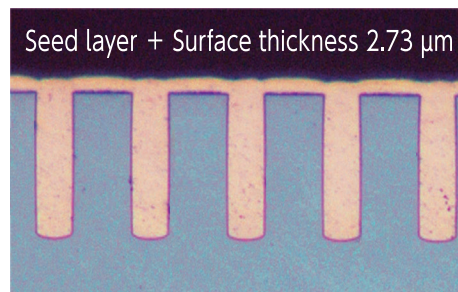
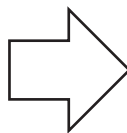
# TOP LUCINA SV



## High aspect filling by small thickness



Plating time : 15 min



Plating time : 30 min

Current density: 0.2 A/dm<sup>2</sup> aperture diameter: 7  $\mu\text{m}$  via depth: 25  $\mu\text{m}$

## Excellent in filling performance into TGV

